

**(54) HYBRID INTEGRATED CIRCUIT DEVICE**

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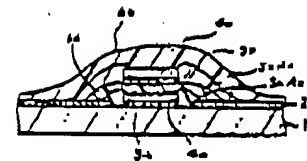
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**PURPOSE:** To obtain a high-density, compact hybrid integrated circuit device, by mounting semiconductor pellets not in a planar arrangement but in a stacked state in two layers through resin.

**CONSTITUTION:** On an insulating substrate 1, on which a wiring conductor 2 is formed, a semiconductor pellet 4 is mounted with a bonding resin 3a. The electrode of the semiconductor pellet 4a and the wiring conductor 2 are bonded with an Au thin wire 5a. Then the semiconductor pellet 4a and the Au thin wire 5a are coated with a coating resin 6a. Thereafter, another semiconductor pellet 4b is mounted on the coating resin 6a, which is coated on the previously provided semiconductor pellet 4a with a bonding resin 3b. Then the pellet is connected with an Au thin wire 5b by the similar way as before. Thereafter, the entire body is coated with a coating resin 6b, and a hybrid integrated circuit device is completed.



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